

# GSM3660EX7F

## 30V N-Channel Enhancement Mode MOSFET

### Product Description

GSM3660E, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer, and low in-line power loss are needed in commercial industrial surface mount applications.

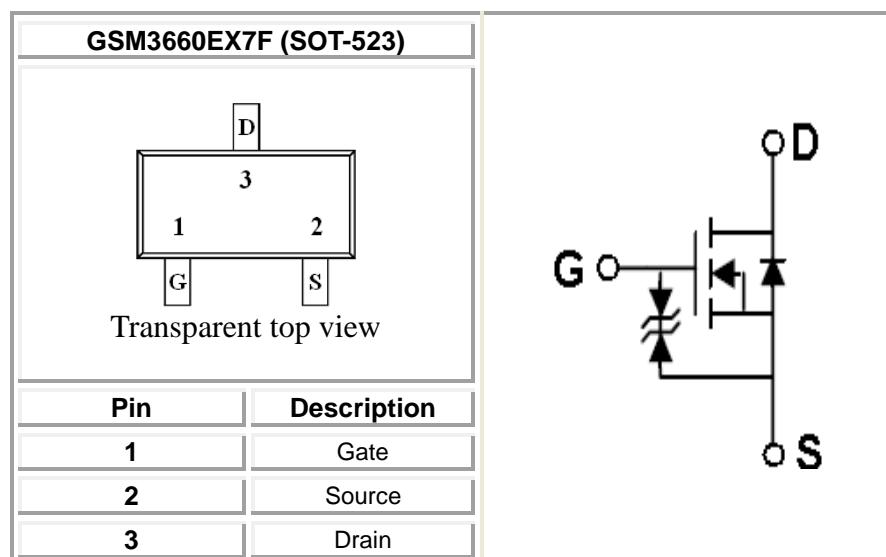
### Features

- Low Gate Charge
- ESD Protected
- SOT-523 package design

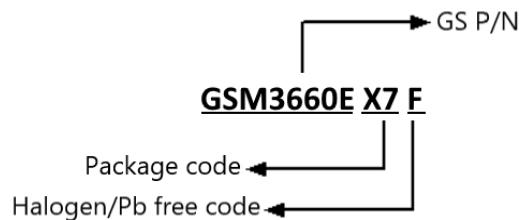
### Applications

- Power Management in Note book
- Portable Equipment
- Load Switch

### Packages & Pin Assignments



## Ordering Information



Part Number	Package	Quantity Reel
GSM3660EX7F	SOT-523	3000 PCS

## Marking Information

Part Number  
**0 WM**  
GS Code

## Absolute Maximum Ratings

(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage	30	V
V <sub>GSS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub>	Continuous Drain Current(T <sub>A</sub> =25°C) <sup>1</sup>	0.51	A
I <sub>DM</sub>	Pulsed Drain Current <sup>3</sup>	2	A
P <sub>D</sub>	Power Dissipation	0.3	W
R <sub>θJA</sub>	Thermal Resistance Junction to ambient <sup>1</sup>	450	°C/W
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

Notes:

1. Surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2oz copper.
2. Pulse width limited by maximum junction temperature, Pulse Width≤300μs, Duty Cycle≤1%.

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## Electrical Characteristics

( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Static</b>							
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5		1.5		
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			10	$\mu\text{A}$	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$			100	$\text{nA}$	
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=0.5\text{A}$		355	600	$\text{m}\Omega$	
		$V_{GS}=4.5\text{V}, I_D=0.4\text{A}$		435	650		
		$V_{GS}=2.5\text{V}, I_D=0.3\text{A}$		665	1200		
$g_{FS}$	Forward Transconductance	$V_{DS}=10\text{V}, I_D=0.5\text{A}$		1.1		S	
$V_{SD}$	Diode Forward Voltage	$I_S=0.25\text{A}, V_{GS}=0\text{V}$			1.35	V	
<b>Dynamic</b>							
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}, V_{GS}=10\text{V}, I_D=0.5\text{A}$		1.5		$\text{nC}$	
$Q_{gs}$	Gate-Source Charge			0.2			
$Q_{gd}$	Gate-Drain Charge			0.2			
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}$ $f=1\text{MHz}$		39		$\text{pF}$	
$C_{oss}$	Output Capacitance			9			
$C_{rss}$	Reverse Transfer Capacitance			6			
$t_{d(on)}$	Turn-On Time	$V_{DD}=15\text{V}, I_D=0.5\text{A}, V_{GS}=10\text{V}, R_G=2.5\Omega$		3		$\text{ns}$	
$t_r$				3			
$t_{d(off)}$	Turn-Off Time			12			
$t_f$				8			

## Typical Performance Characteristics

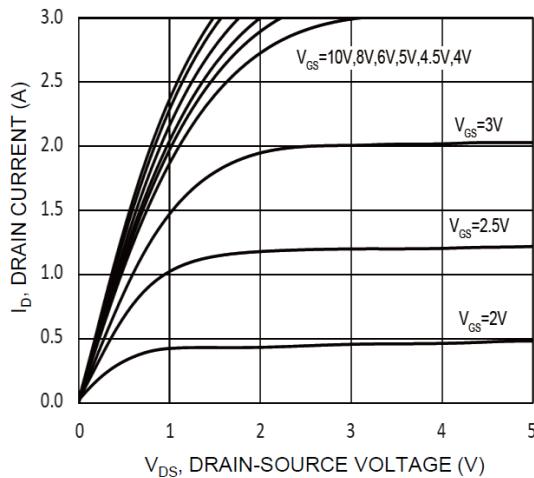


Fig. 1 Typical Output Characteristics

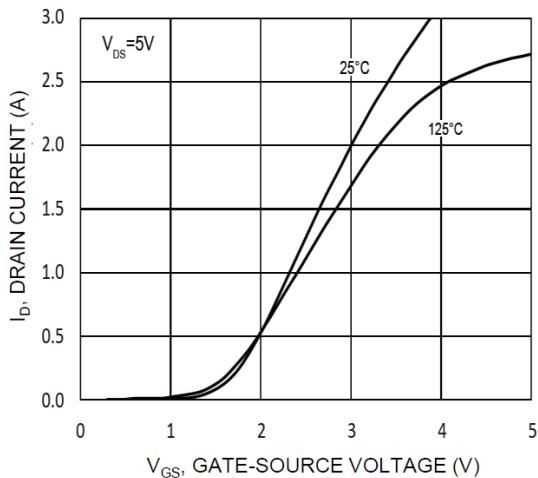


Fig. 2 Typical Transfer Characteristics

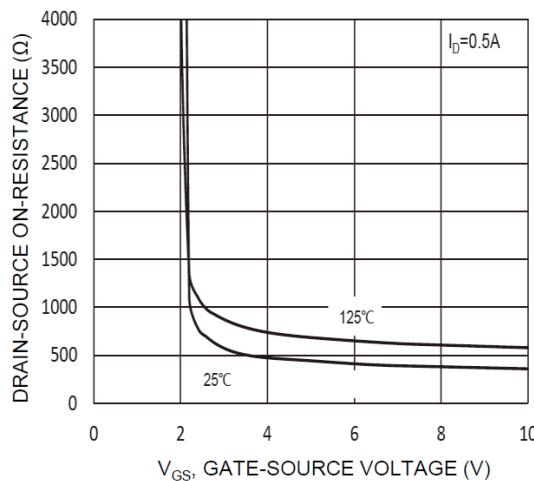


Fig. 3 Typical On-Resistance vs.  $V_{GS}$

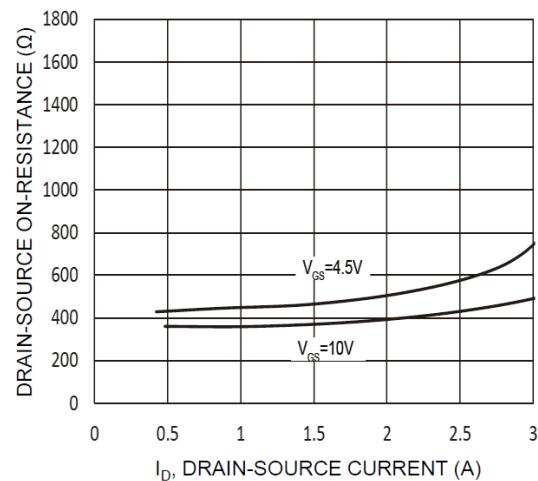


Fig. 4 Typical On-Resistance vs.  $I_D$

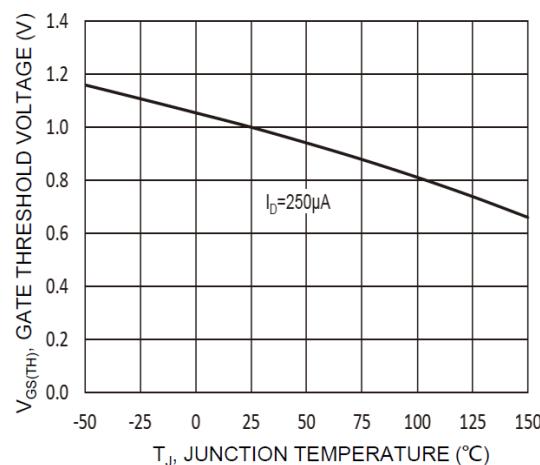


Fig. 5 Normalized Threshold Voltage

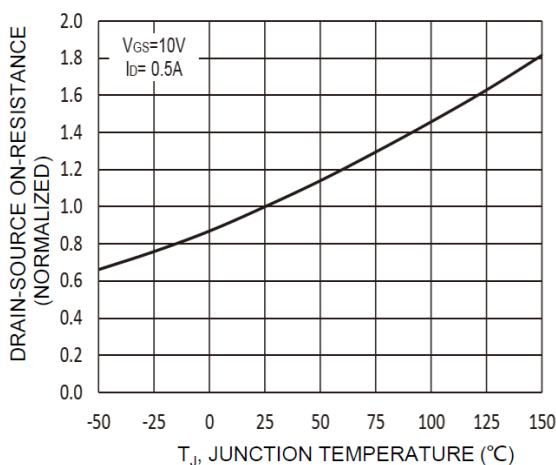


Fig. 6. On-Resistance Variation with  $T_J$

## Typical Performance Characteristics (Continue)

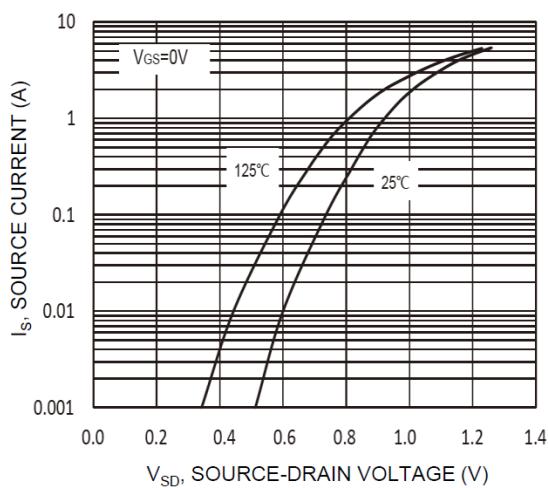


Fig. 7 Diode Forward Voltage vs. Current

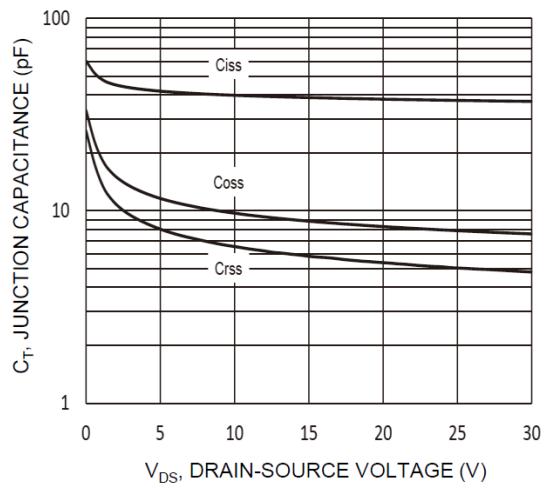


Fig. 8 Typical Capacitance

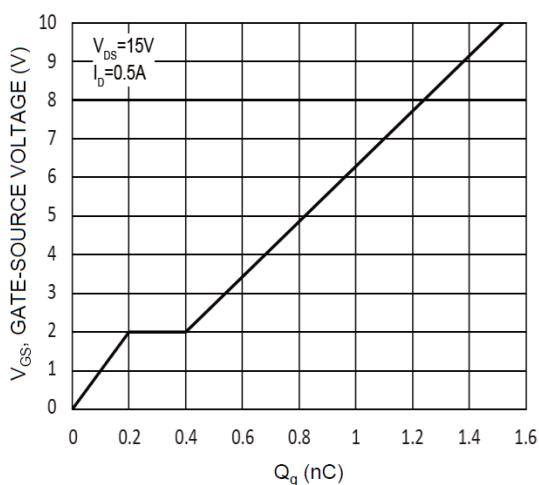


Fig. 9 Gate Charge

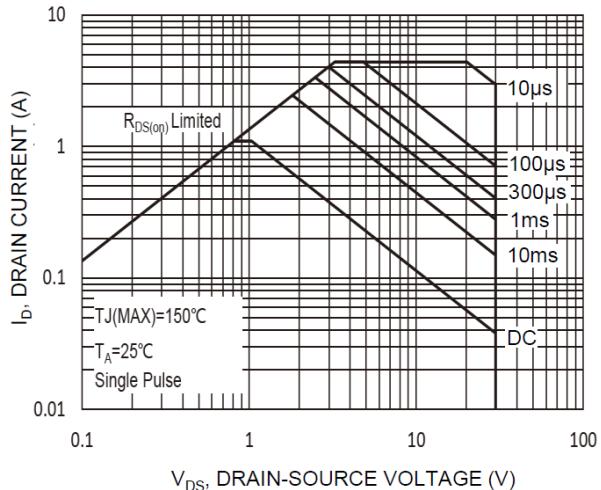


Fig. 10 Safe Operation Area

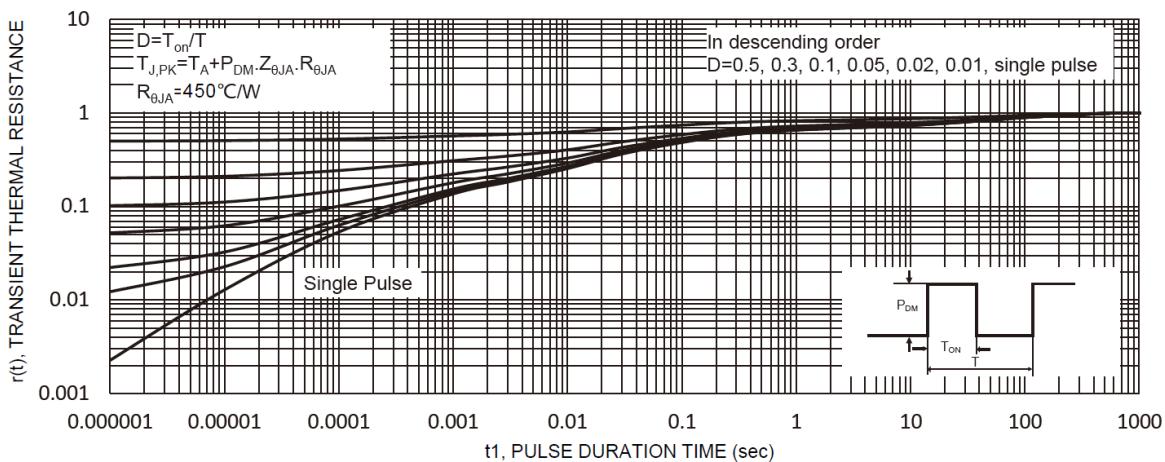
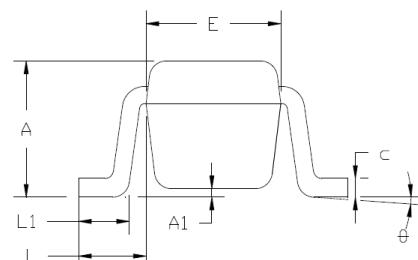
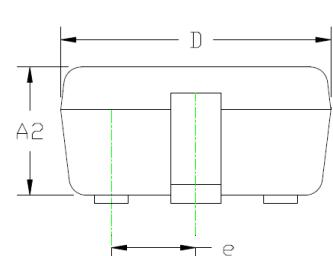
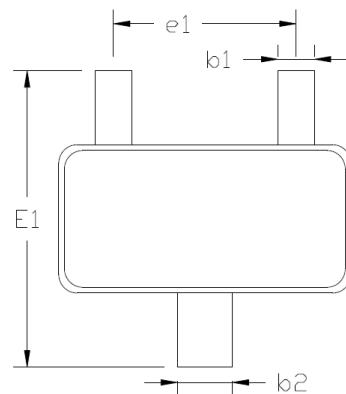


Fig. 11 Transient Thermal Response

## Package Dimension

### SOT-523



#### Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	0.700	0.900	0.028	0.035
<b>A1</b>	0.000	0.100	0.000	0.004
<b>A2</b>	0.700	0.800	0.028	0.031
<b>b1</b>	0.150	0.250	0.006	0.010
<b>b2</b>	0.250	0.350	0.010	0.013
<b>c</b>	0.100	0.200	0.004	0.009
<b>D</b>	1.500	1.700	0.059	0.067
<b>E</b>	0.700	0.900	0.028	0.035
<b>E1</b>	1.450	1.750	0.057	0.068
<b>e</b>	0.500 TYP		0.020 TYP	
<b>e1</b>	0.900	1.100	0.035	0.043
<b>L</b>	0.400 REF		0.021 REF	
<b>L1</b>	0.260	0.460	0.010	0.018
<b>θ</b>	0°	8°	0°	8°

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